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Responsible committee: EPL/47 Semiconductors

Interested committees:

Title: BS EN 62047-55 Ed.1.0 Draft Micro-electromechanical devices. Part 55: Silicon based MEMS fabrication technology - Test method of microstructure pendulum impact.

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Introduction

This draft standard is based on national and international discussions. Your comments on this draft are invited and will assist in the preparation of the consequent standard.

For international standards, comments will be reviewed by the relevant UK national committee before sending the consensus UK vote and comments to the international committee, which will then decide appropriate action. If the international standard is approved, it is usual for the text to be published as a British Standard.

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UK Vote

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/ Figure/Table/Note	Type of comment	Comment (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	



47F/539/CD

COMMITTEE DRAFT (CD)

PROJECT NUMBER: IEC 62047-55 ED1	
DATE OF CIRCULATION: 2025-12-05	CLOSING DATE FOR COMMENTS: 2026-01-30
SUPERSEDES DOCUMENTS: 47F/469/NP, 47F/477A/RVN	

IEC SC 47F : MICRO-ELECTROMECHANICAL SYSTEMS	
SECRETARIAT: Japan	SECRETARY: Mr Takashi Mihara
OF INTEREST TO THE FOLLOWING COMMITTEES:	HORIZONTAL FUNCTION(S):
ASPECTS CONCERNED:	

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TITLE:

Semiconductor devices - Micro-electromechanical devices - Part 55: Silicon based MEMS fabrication technology - Test method of microstructure pendulum impact

NOTE FROM TC/SC OFFICERS:

This draft of CD was made based on the discussion at WG2 held on 25-05-21 in Shijiazhuang, China and the observation of 47F/477A/RVN.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MICRO-ELECTROMECHANICAL DEVICES –****Part 55: Silicon based MEMS fabrication technology –
Test method of microstructure pendulum impact**

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IEC 62047-55 has been prepared by subcommittee 47F: Micro electromechanical systems, of IEC technical committee 47: Semiconductor devices. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
XX/XX/FDIS	XX/XX/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

87 The language used for the development of this International Standard is English.

88 This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in
89 accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available
90 at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are
91 described in greater detail at www.iec.ch/publications.

92 A list of all parts in the IEC 62047 series, published under the general title *Semiconductor*
93 *devices – Micro-electromechanical devices*, can be found on the IEC website.

94 The committee has decided that the contents of this document will remain unchanged until the
95 stability date indicated on the IEC website under webstore.iec.ch in the data related to the
96 specific document. At this date, the document will be

- 97 • reconfirmed,
- 98 • withdrawn,
- 99 • replaced by a revised edition, or
- 100 • amended.

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